SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

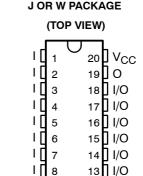
- **High-Performance Operation:** Propagation Delay . . . 15 ns Max
- Power-Up Clear on Registered Devices (All Register Outputs are Set High, but Voltage Levels at the Output Pins Go Low)
- Package Options Include Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) 300-mil DIPs
- **Dependable Texas Instruments Quality and** Reliability

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORTS
PAL16L8	10	2	0	6
PAL16R4	8	0	4 (3-state buffers)	4
PAL16R6	8	0	6 (3-state buffers)	2
PAL16R8	8	0	8 (3-state buffers)	0

description

These programmable array logic devices feature high speed and functional equivalency when compared with currently available devices. These IMPACT-X™ circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allows for quick design of custom functions and typically results in a more compact circuit board. In addition, chip carriers are available for futher reduction in board space.

The TIBPAL16' M series is characterized for operation over the full military temperature range of -55°C to 125°C.



TIBPAL16L8'

TIBPAL16L8' **FK PACKAGE** (TOP VIEW)

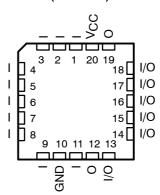
9

10

GND [

12**∏** O

11 🛮 I



Pin assignments in operating mode

IMPORTANT PROGAMMING NOTE: For TIBPAL16L8-15M devices in J, W, or FK packages - For date code 9903A or later device programming, select from either TI Military/16L8-12 or TI commercial TI/16L8-10 on the Manufacturer/Device menu listing in your programming system.

IMPORTANT PROGAMMING NOTE: For TIBPAL16R4-15M devices in J, W, or FK packages - For date code 9616A or later device programming, select from either TI Military/16R4-12 or TI commercial TI /16R4-10 on the Manufacturer/Device menu listing in your programming system.

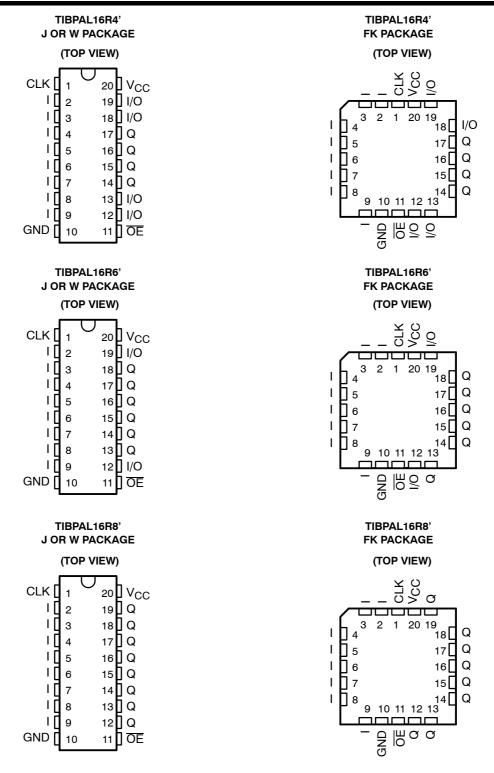


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

IMPACT is a trademark of Texas Instruments Incorporated. PAL is a registered trademark of Advanced Micro Devices Inc



SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011



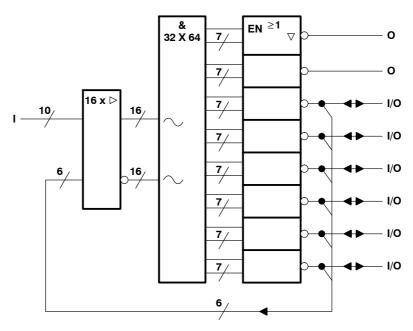
Pin assignments in operating mode



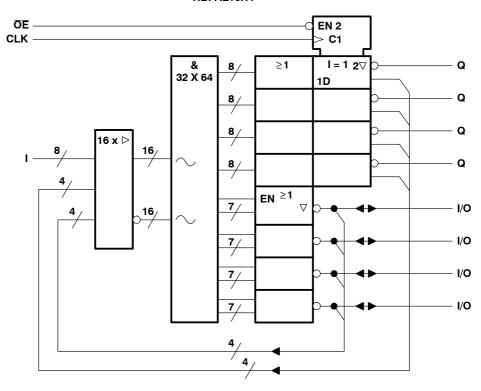
SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

functional block diagrams (positive logic)

TIBPAL16L8



TIBPAL16R4'



 \sim denotes fused inputs

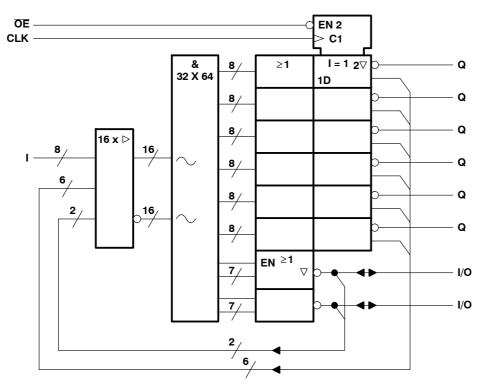


TIBPAL16L8-15M, TIBPAL16R4-15M HIGH-PERFORMANCE IMPACT TM PAL^{\circledR} CIRCUITS

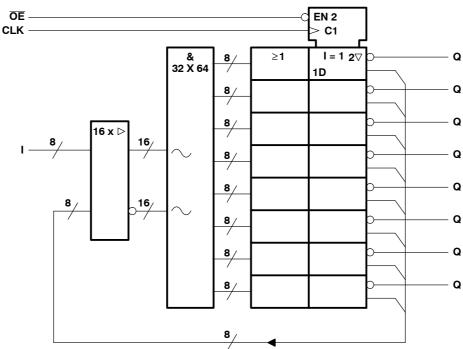
SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

functional block diagrams (positive logic)

TIBPAL16R6'



TIBPAL16R8

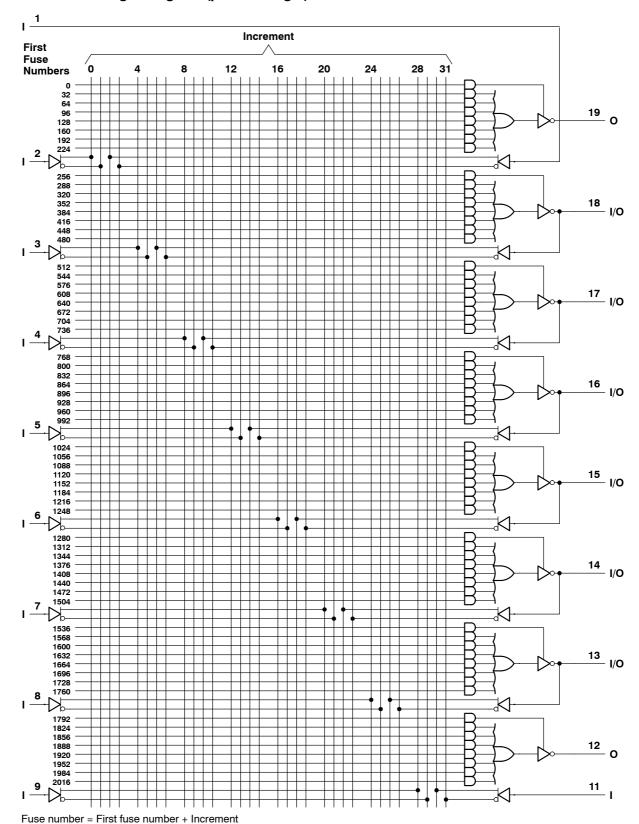


 \sim denotes fused inputs



SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

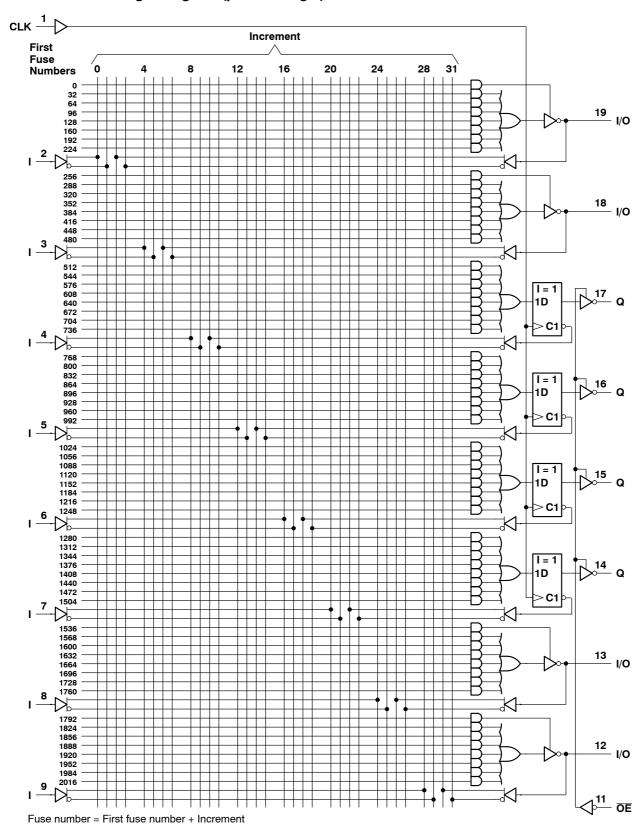
TIBPAL16L8-15M logic diagram (positive logic)





SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

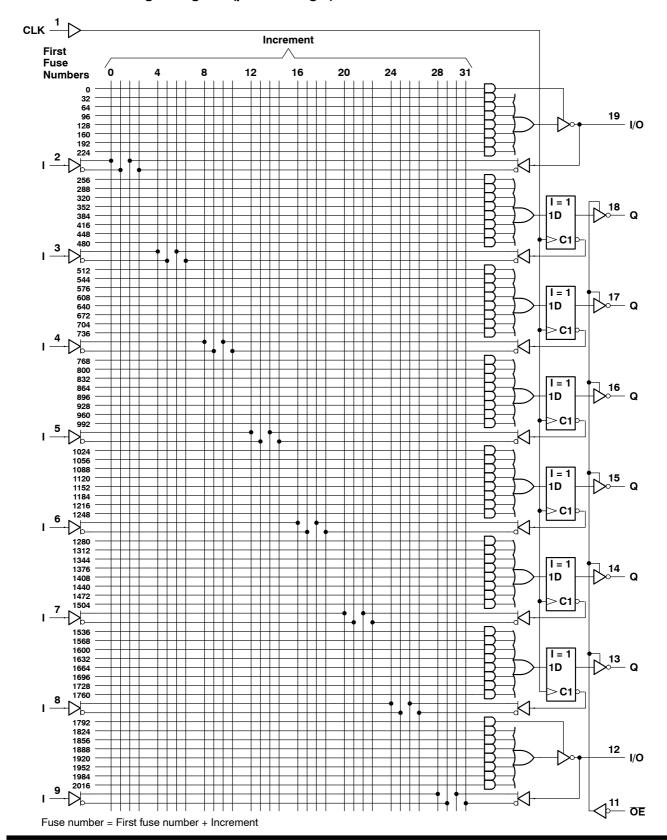
TIBPAL16R4-15M logic diagram (positive logic)



TIBPAL16L8-15M, TIBPAL16R4-15M HIGH-PERFORMANCE $IMPACT \ ^{TM} \ PAL \ ^{\oplus}$ CIRCUITS

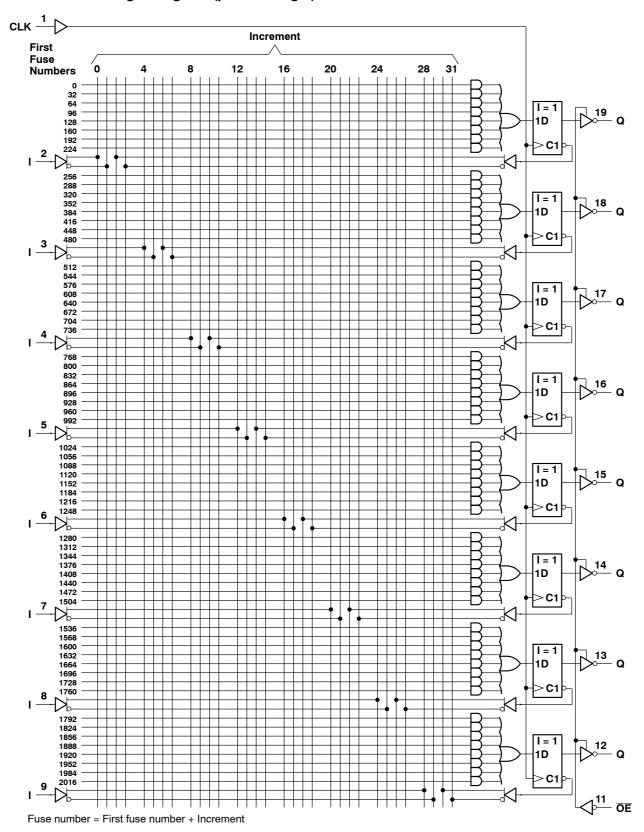
SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

TIBPAL16R6-15M logic diagram (positive logic)



SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

TIBPAL16R8-15M logic diagram (positive logic)



SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

NOTE 1: These ratings apply except for programming pins during a programming cycle.

recommended operating conditions

				MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V		
V _{IH}	High-level input voltage	2		5.5	V		
V_{IL}	Low-level input voltage			8.0	V		
I _{OH}	High-level output current					-2	mA
I _{OL}	Low-level output current			12	mA		
f _{clock}	Clock frequency					50	MHz
	Dulas divistina alasti (asa Nata O)	F	ligh	9			
t _w	Pulse duration, clock (see Note 2)						ns
t _{su}	Setup time, input or feedback before clock↑	15			ns		
t _h	Hold time, input or feedback after clock↑						ns
T _A	Operating free-air temperature			-55	25	125	°C

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock}. The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

electrical characteristics over recommended operating free-air temperature range

PARAMETER			TEST COMPLETIONS				TIBPAL16R4-15M			
			TEST CONDITIO	NS	MIN	MIN TYP [‡] MAX				
V_{IK}		V _{CC} = 4.5 V,	I _I = –18 mA				-1.5	V		
V_{OH}		$V_{CC} = 4.5 V$,	$I_{OH} = -2 \text{ mA}$		2.4	3.3		V		
V_{OL}		$V_{CC} = 4.5 V$,	I _{OL} = 12 mA			0.35	0.5	V		
	Outputs	V 55V	\\ 07\\					_		
l _{OZH}	I/O ports	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 V$	$V_O = 2.7 V$			100	μΑ		
	Outputs	.,					-20	μΑ		
I _{OZL}	I/O ports	$V_{CC} = 5.5 V,$	$V_O = 0.4 V$	V _O = 0.4 V			-250			
	Pin 1, 11	.,), 55V	V _I = 5.5 V						
II	All others	$V_{CC} = 5.5 V,$	V _I = 5.5 V				0.1	mA		
	Pin 1, 11						50			
l _{iH}	I/O ports	V _{CC} = 5.5 V,	$V_{I} = 2.7 \text{ V}$	V _I = 2.7 V		100				
	All others						25	μА		
I _{IL}		V _{CC} = 5.5 V,	V _I = 0.4 V				-0.25	mA		
l _{OS} §		V _{CC} = 5.5 V,	V _O = 0.5 V		-30		-250	mA		
Icc		V _{CC} = 5.5 V,	$V_I = 0$,	Outputs open		170	220	mA		

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

electrical characteristics over recommended operating free-air temperature range

PARAMETER			TEST CONDITIO	ons	TIBP	TIBPAL16L8-15M TIBPAL16R6-15M TIBPAL16R8-15M			
					MIN	MIN TYP† MAX			
V_{IK}		$V_{CC} = 4.5 V$,	$I_I = -18 \text{ mA}$				-1.5	V	
V_{OH}		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$		2.4	3.3		V	
V_{OL}		$V_{CC} = 4.5 \text{ V},$	I _{OL} = 12 mA			0.35	0.5	V	
	Outputs	V 55V	V 07V	V _O = 2.7 V			20	•	
l _{OZH}	I/O ports	V _{CC} = 5.5 V,	$V_0 = 2.7 \text{ V}$				100	μΑ	
	Outputs	V 55V	V 04V				-20	•	
I _{OZL}	I/O ports	V _{CC} = 5.5 V,	$V_0 = 0.4 \text{ V}$				-250	μΑ	
	Pin 1, 11	.,	\\ ==\\					mA	
I _I	All others	$V_{CC} = 5.5 V$,	V _I = 5.5 V	V _I = 5.5 V			0.1		
	Pin 1, 11						50		
I _{IH}	I/O ports	V _{CC} = 5.5 V,	$V_{i} = 2.7 \text{ V}$	V _I = 2.7 V			100 20		
	All others								
	I/O ports							_	
I _{IL}	All others	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 0.4 V$				-0.2	mA	
los [‡]	-	V _{CC} = 5.5 V,	V _O = 0.5 V		-30		-250	mA	
I _{CC}		V _{CC} = 5.5 V,	V _I = 0,	Outputs open		170	220	mA	

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
f _{max} §				50			MHz
t _{pd}	I, I/O	O, I/O			8	15	ns
t _{pd}	CLK↑	Q	R1 = 390 Ω ,		7	12	ns
t _{en}	OE↓	Q	R2 = 750 Ω ,		8	12	ns
t _{dis}	OE↑	Q	See Figure 1		7	12	ns
t _{en}	I, I/O	O, I/O			8	15	ns
t _{dis}	I, I/O	O, I/O		·	8	15	ns

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 $^{\circ}$ C.



[‡] Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

[§] Maximum operating frequency and propagation delay are specified for the basic building block. When using feedback, limits must be calculated accordingly.

SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

The TIBPAL16R4-15M with date codes prior to 9616A must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16R4-12C. The TIBPAL16R4-15M with date code 9616A or newer must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16R4-10C.

Regardless of date code, the TIBPAL16L8-15M, TIBPAL16R6-15M, and TIBPAL16R8-15M must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16L8-12C, TIBPAL16R6-12C, and TIBPAL16R8-12C, respectively. Failure to do so may damage the devices.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

Table 1. Programming Reference Table (see Note 3)

DEVICE	DESC SMD NUMBER	FAMILY/PINOUT CODE
TIBPAL16L8-15MJB	5962-8515509RA	9A/17
TIBPAL16L8-15MFKB	5962-85155092A	9A/717
TIBPAL16L8-15MWB	5962-8515509SA	9A/17
TIBPAL16R4-15MJB	5962-8515512RA	A1/24
TIBPAL16R4-15MFKB	5962-85155122A	0A1/724
TIBPAL16R4-15MWB	5962-8515512SA	A1/24
TIBPAL16R6-15MJB	5962-8515511RA	9A/24
TIBPAL16R6-15MFKB	5962-85155112A	9A/724
TIBPAL16R6-15MWB	5962-8515511SA	9A/24
TIBPAL16R8-15MJB	5962-8515510RA	9A/24
TIBPAL16R8-15MFKB	5962-85155102A	9A/724
TIBPAL16R8-15MWB	5962-8515510SA	9A/24

NOTE 3: Programming information for TIBPAL16R4-15M with date codes 9616A or newer. Programming information for TIBPAL16L8-15M, TIBPAL16R6-15M, and TIBPAL16R8-15M regardless of date code.

SRPS018B - D3338, JANUARY 1986 - REVISED NOVEMBER 2011

Timing

Input

Data

Input

Input

In-Phase

Output

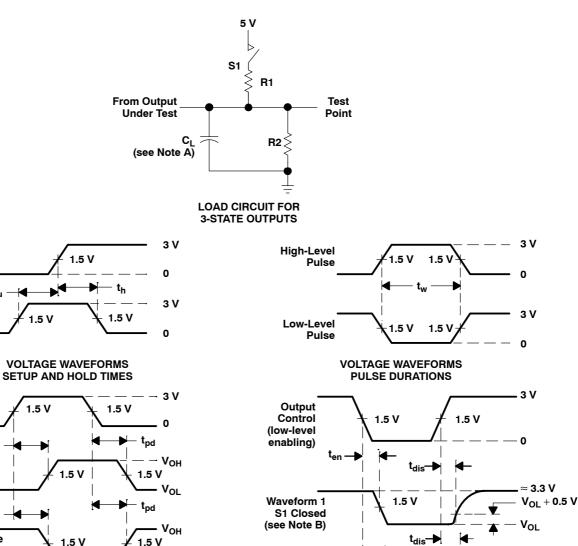
Out-of-Phase

(see Note D)

Output

t_{pd}

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

 V_{OH}

≈ 0 V

V_{OH} – 0.5 V

NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en}, 5 pF for t_{dis}.

1.5 V

 V_{OL}

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Waveform 2 S1 Open

(see Note B)

- C. All input pulses have the following characteristics: PRR \leq 10 MHz, t_r and $t_f \leq$ 2 ns, duty cycle = 50%.
- D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
- E. Equivalent loads may be used for testing.

1.5 V

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

Figure 1. Load Circuit and Voltage Waveforms







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
5962-85155122A	NRND	LCCC	Drawing FK	20	Qty 1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	(4/5) 5962- 85155122A TIBPAL16	
5962-8515512RA	NRND	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	R4-15MFKB 5962-8515512RA TIBPAL16R4-15M JB	
5962-8515512SA	NRND	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8515512SA TIBPAL16R4-15M WB	
TIBPAL16L8-15MJ	NRND	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	TIBPAL16L8-15M J	
TIBPAL16R4-15MFKB	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 85155122A TIBPAL16 R4-15MFKB	
TIBPAL16R4-15MJB	NRND	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8515512RA TIBPAL16R4-15M JB	
TIBPAL16R4-15MWB	NRND	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8515512SA TIBPAL16R4-15M WB	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



PACKAGE OPTION ADDENDUM

6-Feb-2020

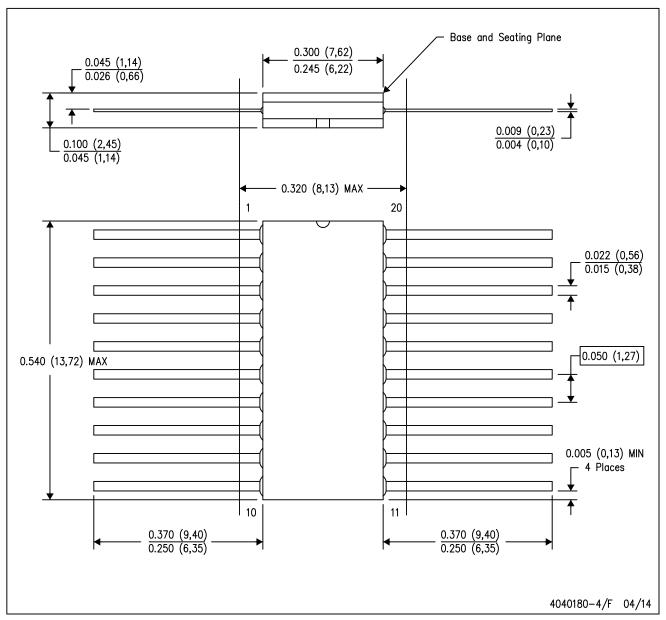
- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated